CM1248-04QG

EDS Protection Diode

Low Capacitance

Features

- Low I/O Capacitance at 10 pF at 0 V
- In-System ESD Protection to ±15 kV Contact Discharge, per the IEC 61000-4-2 International Standard
- Compact SMT Package Saves Board Space and Facilitates Layout in Space–Critical Applications
- Each I/O Pin Can Withstand over 1000 ESD Strikes
- These Devices are Pb-Free and are RoHS Compliant



ON Semiconductor®

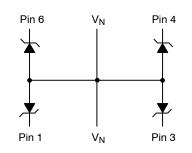
www.onsemi.com



UDFN-6 QG SUFFIX CASE 517BM

BLOCK DIAGRAM





MARKING DIAGRAM



LR = Specific Device Code

ORDERING INFORMATION

| | Device | Package | Shipping [†] |
|---|-------------|--------------------------|-----------------------|
| (| CM1248-04QG | uDFN-0.4 mm (Pb-Free) | 3000/Tape & Reel |

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1248-04QG

PACKAGE / PINOUT DIAGRAMS

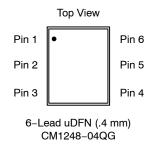


Table 1. PIN DESCRIPTIONS

| Pins | Name | Description |
|--------------------------------------|----------------|---|
| (Refer to package / pinout diagrams) | CHx | The cathode of the respective surge protection diode, which should be connected to the node requiring transient voltage protection. |
| (Refer to package / pinout diagrams) | V _N | The anode of the surge protection diodes. |

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

| Parameter | Rating | Units |
|---------------------------|-------------|-------|
| Storage Temperature Range | –65 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. STANDARD OPERATING CONDITIONS

| Parameter | Rating | Units |
|-----------------------|------------|-------|
| Operating Temperature | -40 to +85 | °C |

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|-------------------|---|---|-----|--------------|------|-------|
| C _{IN} | Channel Input Capacitance | T _A = 25°C, 0 VDC, 1 MHz; Note 2 | | 10 | | pF |
| | | 0 VDC, 1 MHz; Note 1 | 7 | | 15 | pF |
| ΔC_{IN} | Differential Channel I/O to GND Capacitance | T _A = 25°C, 2.5 VDC, 1 MHz; Note 2 | | 0.19 | | pF |
| V _{RSO} | Reverse Stand-off Voltage | I _R = 10 μA, T _A = 25°C | 5.5 | | | V |
| | | I _R = 1 mA, T _A = 25°C | 6.1 | | | V |
| I _{LEAK} | Leakage Current | V_{IN} = 5.0 VDC, T_A = 25°C | | | 0.25 | μA |
| | | V _{IN} = 5.0 VDC, Note 1 | | | 0.75 | μA |
| V _{SIG} | Small Signal Clamp Voltage Positive Clamp Negative Clamp | I = 10 mA, T _A = 25°C I = –10 mA, T _A = 25°C | | 6.8 -0.89 | | V |
| V _{ESD} | ESD Withstand Voltage Contact Discharge per IEC 61000-4-2 standard | T _A = 25°C (Notes 2, 4 and 5) | ±15 | | | kV |
| R _D | Diode Dynamic Resistance Forward Conduction Reverse Conduction | T _A = 25°C (Notes 2 and 3) | | 0.57 1.36 | | Ω |

1. All parameters specified at $T_A = -40^{\circ}C$ to $+85^{\circ}C$ unless otherwise noted. 2. These parameters guaranteed by design and characterization. 3. Human Body Model per MIL-STD-883, Method 3015, $C_{\text{Discharge}} = 100 \text{ pF}$, $R_{\text{Discharge}} = 1.5 \text{ K}\Omega$, V_N grounded. 4. Standard IEC 61000-4-2 with $C_{\text{Discharge}} = 150 \text{ pF}$, $R_{\text{Discharge}} = 330 \Omega$, V_N grounded. 5. These measurements performed with no external capacitor on Pin_X.

CM1248-04QG

PERFORMANCE INFORMATION

Diode Capacitance

Typical diode capacitance with respect to positive cathode voltage (reverse voltage across the diode) is given in Diode Capacitance vs. Reverse Voltage.

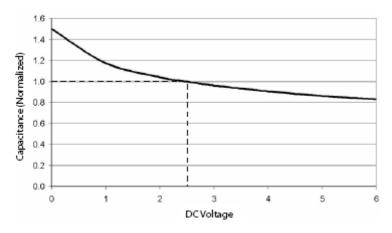


Figure 1. Diode Capacitance vs. Reverse Voltage

Typical High Current Diode Characteristics

Measurements are made in pulsed mode with a nominal pulse width of 0.7 ms.

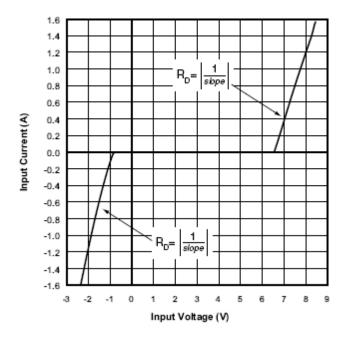
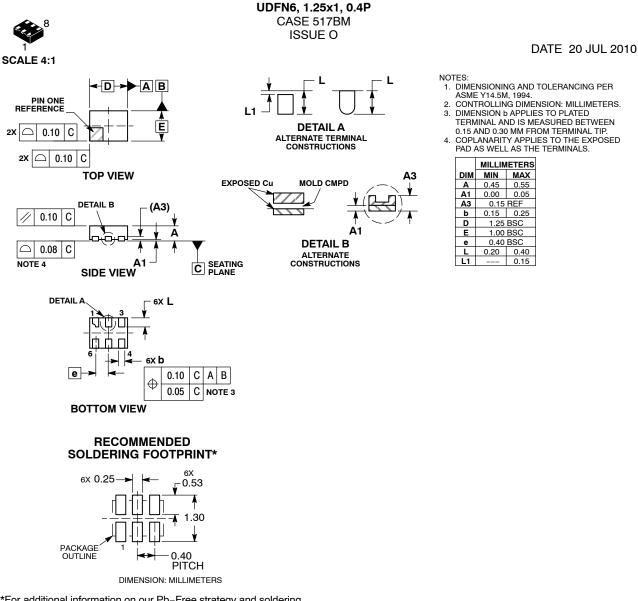


Figure 2. Typical Input VI Characteristics (Pulse-mode Measurements, Pulse Width = 0.7 ms nominal)

<u>Onsemi</u>



*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| DOCUMENT NUMBER: | 98AON48939E | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | | | |
|------------------|---------------------|---|-------------|--|--|
| DESCRIPTION: | UDFN6, 1.25x1, 0.4P | | PAGE 1 OF 1 | | |
| | | | | | |

onsemi and OI ISCITII are trademarks or Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights or the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent_Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com

ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at <u>www.onsemi.com/support/sales</u>